

BCM[™] DC to DC Bus Converter Module



FEATURES

- 384 Vdc 48 Vdc 325 W Bus Converter Module
- High efficiency (>95%) reduces system power consumption
- High power density (>1000 W/in³) reduces power system footprint by >40%
- "Full Chip" V•I Chip package enables surface mount, low impedance interconnect to system board
- Contains built-in protection features: undervoltage, overvoltage lockout, over current protection, short circuit protection, overtemperature protection.
- Provides enable/disable control, internal temperature monitoring
- ZVS/ZCS Resonant Sine Amplitude Converter topology
- Can be paralleled to create multi-kW arrays

TYPICAL APPLICATIONS

- High End Computing Systems
- Automated Test Equipment
- Telecom Base Stations
- High Density Power Supplies
- Communication Systems

TYPICAL APPLICATION

lvc VC SG OS PR] РС 1PC PC enable / disable CD L ТМ Ξтм switch] IL 0 PRM SWI BCM VTM Α +In +Out +In +Out +Out C1 1 µF D -In -Out -Out -In -00 -In



DESCRIPTION

The V•I Chip Bus Converter Module is a high efficiency (>95%) Sine Amplitude Converter (SAC) operating from a 360 to 400 Vdc primary bus to deliver an isolated 45-50 V nominal, unregulated secondary. The SAC offers a low AC impedance beyond the bandwidth of most downstream regulators, meaning that input capacitance normally located at the input of a regulator can be located at the input to the SAC. Since the K factor of the VIB0002TFJ is 1/8, that capacitance value can be reduced by a factor of 64x, resulting in savings of board area, materials and total system cost.

The VIB0002TFJ is provided in a V•I Chip package compatible with standard pick-and-place and surface mount assembly processes. The V•I Chip package provides flexible thermal management through its low junction-to-case and junction-toboard thermal resistance. With high conversion efficiency the VIB0002TFJ increases overall system efficiency and lowers operating costs compared to conventional approaches.

$V_{IN} = 360 - 400 V$	$P_{out} = 325 \text{ W(nom)}$
V _{OUT} = 45.0 - 50.0 V	K = 1/8

ABSOLUTE MAXIMUM RATINGS

+IN to –IN \ldots	1.0 Vdc – +440 Vdc
PC to –IN	0.3 Vdc – +20 Vdc
TM to $-IN$	0.3 Vdc – +7.0 Vdc
+IN/-IN to +OUT/-OUT	4242 V (Hi Pot)
+IN/-IN to +OUT/-OUT	500 V (working)
+OUT to -OUT	1.0 Vdc - +60 Vdc
Temperature during reflow	

PACKAGE ORDERING INFORMATION



PART NUMBER	DESCRIPTION
VIB0002TFJ	-40°C – 125°C T _J , J lead

CONTROL PIN SPECIFICATIONS

See section 5.0 for further application details and guidelines.

PC (V•I Chip BCM Primary Control)

The PC pin can enable and disable the BCM. When held below V_{PC-DIS} the BCM shall be disabled. When allowed to float with an impedance to –IN of greater than 50 k Ω the module will start. When connected to another BCM PC pin, the BCMs will start simultaneously when enabled. The PC pin is capable of being either driven high by an external logic signal or internal pull up to 5 V (operating).

TM (V•I Chip BCM Temperature Monitor)

The TM pin monitors the internal temperature of the BCM within an accuracy of +5/-5 °C. It has a room temperature setpoint of ~3.0 V and an approximate gain of 10 mV/°C. It can source up to 100 uA and may also be used as a "Power Good" flag to verify that the BCM is operating.



1.0 ELECTRICAL CHARACTERISTICS

Specifications apply over all line and load conditions unless otherwise noted; **Boldface** specifications apply over the temperature range of -40°C < T_J < 125°C (T-Grade); All other specifications are at T_J = 25° unless otherwise noted

ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	ТҮР	MAX	UNIT	
Voltage range	VIN		360	384	400	Vdc	
dV/dt	dV _{IN} /dt				1	V/µs	
Quiescent power	PQ	PC connected to -IN		395	410	mW	
Ne les du sur d'acte di su	P	V _{IN} = 384 V		6.5	10	14/	
No load power dissipation	P _{NL}	V _{IN} = 360 to 400 V			13.5	VV	
Inrush Current Peak	I _{INR-P}	$V_{IN} = 400 \text{ V } C_{OUT} = 100 \mu\text{F},$ $P_{OUT} = 325 \text{ W}$		2.0	4	А	
DC Input Current	I _{IN-DC}				1.0	А	
K Factor $\left(\frac{V_{OUT}}{V_{IN}}\right)$	К			1/8			
Output Power (Average)	P _{OUT}	V_{IN} = 384 Vdc; See Figure 12 V_{IN} = 360 – 400 Vdc; See Figure 12			325 300	W	
Output Power (Peak)	P _{OUT-P}	V _{IN} = 384 Vdc Average P _{OUT} < = 325 W, Tpeak < 5 ms			495	W	
Output Voltage	Vout	Section 3.0 No load	45.0		50.0	V	
Output Current (Average)	I _{OUT}	Pout < =325 W			7.05	A	
		V _{IN} = 384 V, P _{OUT} = 300 W	94.2	95.8		0/	
Efficiency (Ambient)	η	$V_{\rm IN} = 360 \text{ V to } 400 \text{ V}, P_{\rm OUT} = 325 \text{ W}$	94.2			%	
Efficiency (Hot)	η	VIN = 384 V, T _J = 100° C, P _{OUT} = 325 W	94.0	95.3		%	
Minimum Efficiency (Over Load Range)	η	60 W < P _{OUT} < 325 W Max	90			%	
Output Resistance (Ambient)	R _{OUT}	T _J = 25° C	100	160	200	mΩ	
Output Resistance (Hot)	R _{OUT}	T _J = 125° C	150	220	270	mΩ	
Output Resistance (Cold)	R _{OUT}	$T_J = -40^\circ C$	60	120	180	mΩ	
Load Capacitance	C _{OUT}				100	uF	
Switching Frequency	F _{SW}		1.66	1.75	1.83	MHz	
Ripple Frequency	F _{SW-RP}		3.33	3.50	3.66	MHz	
Output Voltage Ripple	V _{OUT-PP}	$C_{OUT} = 0 \ \mu\text{F}, P_{OUT} = 325 \ \text{W}, V_{IN} = 384 \ \text{V},$ Section 8.0		180	400	mV	
V_{IN} to V_{OUT} (Application of $V_{\text{IN}})$	T _{ON1}	V_{IN} = 380 V, C_{PC} = 0; See Figure 14	460	540	620	ms	
PC Voltage (Operating)	Vpc		17	5.0	52		
PC Voltage (Enable)			2.0	2.5	3.0	V \/	
PC Voltage (Disable)	VPC-EN		2.0	2.5	1 95	V \/	
PC Source Current (Startup)			50	100	300		
PC Source Current (Operating)			2	3 5	5	mΔ	
PC Internal Resistance	RPC-SNK	Internal pull down resistor	50	150	400	kQ	
PC Capacitance (Internal)		Section 5.0		150	1000	nF	
PC Capacitance (External)		External capacitance delays PC enable time			1000	Pi	
External PC Resistance	Rec	Connected to -Vm	50		1000	k0	
PC External Togole Rate	EPC-TOG				1	H7	
	· rc-100	Vw = 384 V Pre-applied			•	112	
PC to V _{OUT} with PC Released	Ton2	$C_{PC} = 0, C_{OUT} = 0;$ See Figure 14	50	100	150	μs	
PC to V_{OUT} , Disable PC	T _{PC-DIS}	$v_{IN} = 384$ V, Pre-applied $C_{PC} = 0$, $C_{OUT} = 0$; See Figure 14		4	10	μs	



1.0 ELECTRICAL CHARACTERISTICS (CONT.)

Specifications apply over all line and load conditions unless otherwise noted; **Boldface** specifications apply over the temperature range of $-40^{\circ}C < T_J < 125^{\circ}C$ (T-Grade); All other specifications are at $T_J = 25^{\circ}$ unless otherwise noted

ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	ТҮР	MAX	UNIT
тм						
	Actm		5		+5	°C
	Δτι		-5	10	÷J	m\//°C
			100	10		
TM Internal Resistance	BTN CNW		25	40	50	k O
External TM Capacitance	CTM-SNK		25	40	50	nE
TM Voltage Ripple	V _{TM-PP}	$C_{TM} = 0\mu$ F, $V_{IN} = 400$ V, $P_{OUT} = 325$ W	200	400	500	mV
PROTECTION						
Negative going OVLO			400	420	430	V
Positive going OVLO			420	430	440	V
Negative going UVLO			270	285	304	V
Positive going UVLO	VIN UVLO+		290	310	330	V
Output Overcurrent Trip	I _{OCP}	V _{IN} = 384 V, 25°C	9	11	14	A
Short Circuit Protection Trip Current	I _{SSP}		14			А
Short Circuit Protection Response Time	T _{SSP}		0.8	1.0	1.2	us
Thermal Shutdown Junction setpoint	T _{J-OTP}		125	130	135	°C
GENERAL SPECIFICATION						
Isolation Voltage (Hi-Pot)	V _{HIPOT}		4242			V
Working Voltage (IN – OUT)	Vworking				500	V
Isolation Capacitance	C _{IN-OUT}	Unpowered unit	500	660	800	pF
Isolation Resistance	R _{IN-OUT}		10			MΩ
MTBF		MIL HDBK 217F, 25° C, GB		4.2		Mhrs
		cTUVus				
Agency Approvals/Standards		CE Mark				
		ROHS 6 of 6				



1.1 APPLICATION CHARACTERISTICS

All specifications are at $T_J = 25^{\circ}$ unless otherwise noted. See associated figures for general trend data.

ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	ТҮР	UNIT
No Load Power	P _{NL}	V _{IN} = 384 V, PC enabled; See Figure 1	10	W
Inrush Current Peak	I _{NR-P}	C _{OUT} = 100 μF, P _{OUT} = 325 W	4	A
Efficiency (Ambient)	η	$V_{IN} = 384 \text{ V}, P_{OUT} = 325 \text{ W}$ $C_{OUT} = 100 \mu\text{F}$	95.5	%
Efficiency (Hot – 100°C)	η	$V_{IN} = 384 \text{ V}, P_{OUT} = 325 \text{ W}$ $C_{OUT} = 100 \mu\text{F}$	95	%
Output Resistance (-40°C)	Rout_c	V _{IN} = 384 V	130	mΩ
Output Resistance (25°C)	R _{OUT_R}	V _{IN} = 384 V	170	mΩ
Output Resistance (100°C)	R _{OUT_H}	V _{IN} = 384 V	235	mΩ
Output Voltage Ripple	V _{OUT-PP}	C_{OUT} = 0uF, P_{OUT} = 325 W @ $V_{\rm IN}$ = 384, $V_{\rm IN}$ = 384 V	160	mV
V _{OUT} Transient (Positive)	V _{OUT-TRAN+}	I _{OUT_STEP} = 0 to 7.05 A [,] I _{SLEW} >10 A/us; See Figure 9	1.5	V
V _{OUT} Transient (Negative)	V _{OUT-TRAN-}	$I_{OUT_STEP} = 7.05 \text{ A to 0 A},$ $I_{SLEW} > 10 \text{ A/us; See Figure 10}$	1.5	V
Undervoltage Lockout Response Time	T _{UVLO}		150	us
Output Overcurrent Response Time	T _{OCP}	9 < I _{OCP} < 14 A	5	ms
Overvoltage Lockout Response Time	T _{OVLO}		120	μs





Figure 1 – No load power dissipation vs. V_{IN}; T_{CASE}



Figure 3a – Efficiency and power dissipation at 25°C (case); V_{IN}







Figure 2 – Full load efficiency vs. temperature; V_{IN}



Figure 3b – Efficiency and power dissipation at –40°C (case); V_{IN}



Figure 4 – R_{OUT} vs. temperature vs. I_{OUT}





Figure 5 – Vripple vs. I_{OUT}; 384 Vin, no external capacitance



Figure 7 – V_{IN} to V_{OUT} startup waveform



Figure 9 – Positive load transient (0 – 7 A)



Figure 6 – PC to V_{OUT} startup waveform



Figure 8 – Output voltage and input current ripple, 384 Vin, 320 W no C_{OUT}



Figure 10 – Negative load transient (7 A – 0 A)





Figure 11 – PC disable waveform, 384 V_{IN}, 100 μ F C_{OUT} full load



Figure 12 – P_{OUT} derating vs. V_{IN}

2.0 PACKAGE/MECHANICAL SPECIFICATIONS

All specifications are at TJ=25° unless otherwise noted. See associated figures for general trend data.

ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	ТҮР	MAX	UNIT
Length	L		32.4 / 1.27	32.5 / 1.28	32.6 / 1.29	mm/in
Width	W		21.7 / 0.85	22.0/0.87	22.3/0.89	mm/in
Height	Н		6.2 / 0.24	6.6/0.26	7.0/0.28	mm/in
Volume	Vol	No Heatsink		4.8/0.290		cm ³ /in ³
Footprint	F	No Heatsink		7.3 / 1.1		cm²/in²
Bower Depsity	Po	No Heatsink			1121	W/in ³
Fower Density	FD	NOTIEAUSITIK			68	W/cm³
Weight	W			0.5/14		oz/g
Lead Finish		Nickel (0.51-2.03 um) Palladium (0.8-6 um) Gold (0.003-0.05 um)				
Operating Temperature	ΤJ		-40		125	°C
Storage Temperature	T _{ST}		-40		125	°C
Thermal Capacity				9		Ws/°C
Peak Compressive Force Applied to Case (Z-axis)		No J-lead support		5	6	lbs
Moisture Sensitivity Level			5			
Peak Temperature During Reflow		MSL Level 5			225	°C
Peak Time Above 183°C					150	S
Peak Heating Rate During Reflow				1.5	3	°C/s
Peak Cooling Rate Post Reflow				1.5	6	°C/s
Thermal Impedance	Ø _{JC}	Min Board Heatsinking		1.1	1.5	°CW



2.1 MECHANICAL DRAWING



2.2 RECOMMENDED LAND PATTERN





3.0 POWER, VOLTAGE, EFFICIENCY RELATIONSHIPS

Because of the high frequency, fully resonant SAC topology, power dissipation and overall conversion efficiency of BCM converters can be estimated as shown below.

Key relationships to be considered are the following:

- 1. Transfer Function
 - a. No load condition

 $V_{OUT} = V_{IN} \bullet K$ Eq. 1

Where K (transformer turns ratio) is constant for each part number

b. Loaded condition

 $V_{OUT} = Vin \bullet K - I_{OUT} \bullet R_{OUT}$ Eq. 2

2. Dissipated Power

The two main terms of power losses in the BCM module are:

- No load power dissipation (P_{NL}) defined as the power used to power up the module with an enabled power train at no load.
- Resistive loss (R_{OUT}) refers to the power loss across the BCM modeled as pure resistive impedance.

 $P_{\text{DISSIPATED}} \approx P_{\text{NL}} + P_{\text{R}_{\text{OUT}}}$ Eq. 3

Therefore, with reference to the diagram shown in Figure 13

 $P_{OUT} = P_{IN} - P_{DISSIPATED} = P_{IN} - P_{NL} - P_{R_{OUT}}$ Eq. 4

Notice that R_{OUT} is temperature and input voltage dependent and P_{NL} is temperature dependent (See Figure 13).



Figure 13 – Power transfer diagram

The above relations can be combined to calculate the overall module efficiency:

$$\eta = \frac{P_{OUT}}{P_{IN}} = \frac{P_{IN} - P_{NL} - P_{ROUT}}{P_{IN}} = \frac{V_{IN} \bullet I_{IN} - P_{NL} - (I_{OUT})^2 \bullet R_{OUT}}{V_{IN} \bullet I_{IN}} = 1 - \left(\frac{P_{NL} + (I_{OUT})^2 \bullet R_{OUT}}{V_{IN} \bullet I_{IN}}\right)$$
Eq. 5



4.0 OPERATING



Figure 14 – Timing diagram



5.0 USING THE CONTROL SIGNALS TM AND PC

The PC control pin can be used to accomplish the following functions:

- **Delayed start:** At start-up, PC pin will source a constant 100 uA current to the internal RC network. Adding an external capacitor will allow further delay in reaching the 2.5 V threshold for module start.
- Synchronized start up: In a parallel module array, PC pins shall be connected in order to ensure synchronous start of all the units. While every controller has a calibrated 2.5 V reference on PC comparator, many factors might cause different timing in turning on the 100 uA current source on each module, i.e.:
 - Different V_{IN} slew rate
 - Statistical component value distribution
 By connecting all PC pins, the charging transient will be shared and all the modules will be enabled synchronously.
- Auxiliary voltage source: Once enabled in regular operational conditions (no fault), each BCM PC provides a regulated 5 V, 2 mA voltage source.
- Output Disable: PC pin can be actively pulled down in order to disable module operations. Pull down impedance shall be lower than 850 Ω and toggle rate lower than 1 Hz.
- Fault detection flag: The PC 5 V voltage source is internally turned off as soon as a fault is detected. After a minimum disable time, the module tries to re-start, and PC voltage is re-enabled. For system monitoring purposes (microcontroller interface) faults are detected on falling edges of PC signal. It is important to notice that PC doesn't have current sink capability (only 150 k Ω typical pull down is present), therefore, in an array, PC line will not be capable of disabling

all the modules if a fault occurs on one of them.

The temperature monitor (TM) pin provides a voltage proportional to the absolute temperature of the converter control IC. It can be used to accomplish the following functions:

- Monitor the control IC temperature: The temperature in Kelvin is equal to the voltage on the TM pin scaled by x100. (i.e. 3.0 V = 300 K = 27°C). It is important to remember that V•I chips are multi-chip modules, whose temperature distribution greatly vary for each part number as well with input/output conditions, thermal management and environmental conditions. Therefore, TM cannot be used to thermally protect the system.
- Fault detection flag: The TM voltage source is internally turned off as soon as a fault is detected. After a minimum disable time, the module tries to re-start, and TM voltage is re-enabled.

6.0 FUSE SELECTION

V•I Chips are not internally fused in order to provide flexibility in configuring power systems. Input line fusing of V•I Chips is recommended at system level, in order to provide thermal protection in case of catastrophic failure.

The fuse shall be selected by closely matching system requirements with the following characteristics:

- Current rating (usually greater than maximum BCM current)
- Maximum voltage rating (usually greater than the maximum possible input voltage)
- Ambient temperature
- Nominal melting I²t
- Recommended fuse: <2.5 A Bussmann PC-Tron or SOC type 36CFA.



7.0 CURRENT SHARING

The SAC topology bases its performance on efficient transfer of energy through a transformer, without the need of closed loop control. For this reason, the transfer characteristic can be approximated by an ideal transformer with some resistive drop and positive temperature coefficient.

This type of characteristic is close to the impedance characteristic of a DC power distribution system, both in behavior (AC dynamic) and absolute value (DC dynamic).

When connected in an array (with same K factor), the BCM module will inherently share the load current with parallel units, according to the equivalent impedance divider that the system implements from the power source to the point of load.

It is important to notice that, when successfully started, BCMs are capable of bidirectional operations (reverse power transfer is enabled if the BCM input falls within its operating range and the BCM is otherwise enabled). In parallel arrays, because of the resistive behavior, circulating currents are never experienced, because of energy conservation law.

General recommendations to achieve matched array impedances are (see also AN016 for further details):

- to dedicate common copper planes within the PCB to deliver and return the current to the modules
- to make the PCB layout as symmetric as possible
- to apply same input/output filters (if present) to each unit



Figure 15 – BCM Array



8.0 INPUT AND OUTPUT FILTER DESIGN

A major advantage of SAC systems versus conventional PWM converters is that the transformers do not require large functional filters. The resonant LC tank, operated at extreme high frequency, is amplitude modulated as a function of input voltage and output current, and efficiently transfers charge through the isolation transformer. A small amount of capacitance, embedded in the input and output stages of the module, is sufficient for full functionality and is key to achieve power density.

This paradigm shift requires system design to carefully evaluate external filters in order to:

1. Guarantee low source impedance:

To take full advantage of the BCM dynamic response, the impedance presented to its input terminals must be low from DC to approximately 5 MHz. The connection of the V•I Chip to its power source should be implemented with minimal distribution inductance. If the interconnect inductance exceeds 100 nH, the input should be bypassed with a RC damper to retain low source impedance and stable operation. With an interconnect inductance of 200 nH, the RC damper may be as high as 1 μ F in series with 0.3 Ω . A single electrolytic or equivalent low-Q capacitor may be used in place of the series RC bypass.

2.Further reduce input and/or output voltage ripple without sacrificing dynamic response:

Given the wide bandwidth of the BCM, the source response is generally the limiting factor in the overall system response. Anomalies in the response of the source will appear at the output of the BCM multiplied by its K factor. This is illustrated in Figures 9 and 10.

3. Protect the module from overvoltage transients imposed by the system that would exceed maximum ratings and cause failures:

The V•I Chip input/output voltage ranges shall not be exceeded. An internal overvoltage lockout function prevents operation outside of the normal operating input range. Even during this condition, the powertrain is exposed to the applied voltage and power MOSFETs must withstand it. A criterion for protection is the maximum amount of energy that the input or output switches can tolerate if avalanched. Total load capacitance at the output of the BCM shall not exceed the specified maximum. Owing to the wide bandwidth and low output impedance of the BCM, low frequency bypass capacitance and significant energy storage may be more densely and efficiently provided by adding capacitance at the input of the BCM. At frequencies <500 kHz the BCM appears as an impedance of R_{OUT} between the source and load. Within this frequency range capacitance at the input appears as effective capacitance on the output per the relationship defined in Eq. 5.

$$C_{OUT} = \frac{C_{IN}}{K^2}$$
 Eq. 6

This enables a reduction in the size and number of capacitors used in a typical system.





Figure 16 – BCM block diagram



Warranty

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